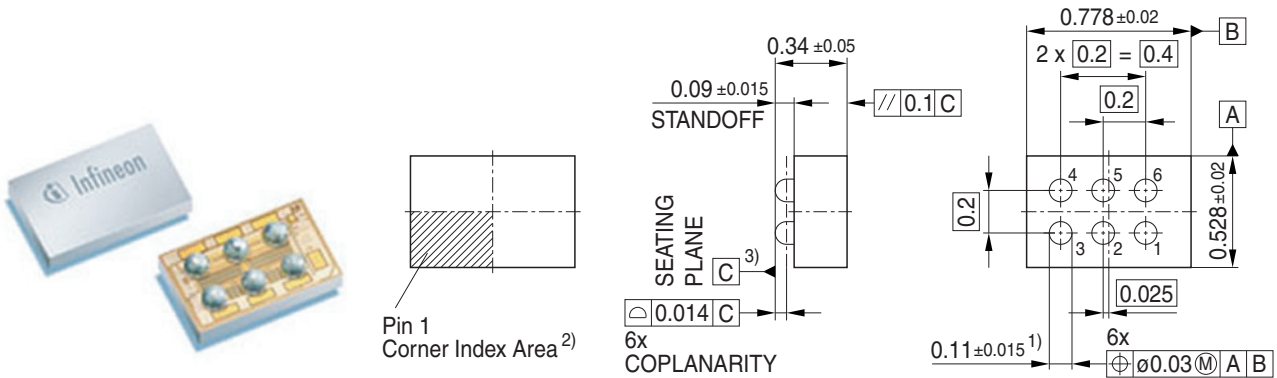


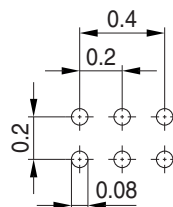
## Package Outline



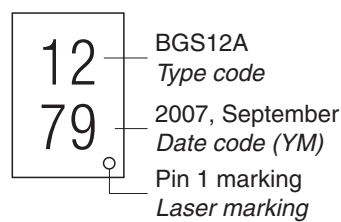
- 1) Dimension is measured at the maximum solder ball diameter, parallel to primary datum C
- 2) Pin1 corner identified by marking
- 3) Primary datum C and seating plane are defined by the domed crowns of the balls

## Foot Print

Soldering Type: Reflow Soldering

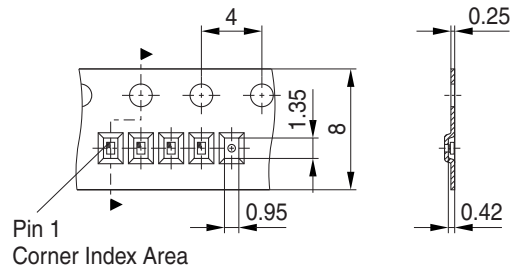


## Marking Layout (Example)



## Tape and Reel

Reel  $\varnothing$ 180 mm: 7.500 Pieces/Reel  
 Reels/Box: 1



Wafer  $\varnothing$ 200 mm: 63.597 Pieces/Wafer

